

# Matched Monolithic Quad Transistor

**MAT-04** 

#### **FEATURES**

•	Low Offset Voltage	200	<b>)</b> μ <b>V</b>	Мах
	High Current Gain		•	
•	Excellent Current Gain Match		2%	Мах
	Low Noise Voltage at 100Hz, 1mA			
•	Excellent Log Conformance	rBE = 0	<b>.6</b> Ω	Мах
	Matching Guaranteed for All Transistors			
•	Available in Die Form			

#### ORDERING INFORMATION †

T .05°C	PACK	AGE	ODEDATING
T <sub>A</sub> = +25°C V <sub>OS</sub> MAX (μV)	CERDIP 14-PIN	PLASTIC 14-PIN	OPERATING TEMPERATURE RANGE
200	MAT04AY*	_	MIL
200	MAT04EY		IND
400	MAT04BY*	_	MIL
400	MAT04FY	MAT04FP	XIND
400		MAT04FS <sup>††</sup>	XIND

- \* For devices processed in total compliance to MIL-STD-883, add/883 after part number. Consult factory for 883 data sheet.
- Burn-in is available on commercial and industrial temperature range parts in CerDIP, plastic DIP, and TO-can packages.
- the For availability and burn-in information on SO and PLCC packages, contact your local sales office.

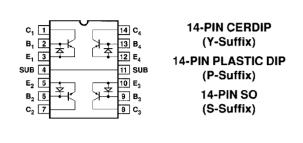
#### **GENERAL DESCRIPTION**

The MAT-04 is a quad monolithic NPN transistor that offers excellent parametric matching for precision amplifier and nonlinear circuit applications. Performance characteristics of the MAT-04 include high gain (400 minimum) over a wide range of collector current, low noise (2.5nV/ $\sqrt{\mbox{Hz}}$  maximum at 100Hz,  $I_C=1$  mA) and excellent logarithmic conformance. The MAT-04 also features a low offset voltage of 200 $\mu$ V and tight current gain matching, to within 2%. Each transistor of the MAT-04 is individually tested to data sheet specifications. For matching parameters (offset voltage, input offset current, and gain match), each of the dual transistor combinations are verified to meet stated limits. Device performance is guaranteed at 25°C and over the industrial and military temperature ranges.

The long-term stability of matching parameters is guaranteed by the protection diodes across the base-emitter junction of each transistor. These diodes prevent degradation of beta and matching characteristics due to reverse bias base-emitter current.

The superior logarithmic conformance and accurate matching characteristics of the MAT-04 makes it an excellent choice for use in log and antilog circuits. The MAT-04 is an ideal choice in applications where low noise and high gain are required.

#### **PIN CONNECTIONS**



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Collector-Base Voltage (BV <sub>CBO</sub> )	40V
Collector-Base Voltage (BV <sub>CBO</sub> ) Collector-Emitter Voltage (BV <sub>CEO</sub> )	40V
Collector-Collector Voltage (BV <sub>CC</sub> )	40V
Emitter-Emitter Voltage (BV <sub>FF</sub> )	40V
Collector Current	
Emitter Current	30mA
Substrate (Pin-4 to Pin-11) Current	30mA
Operating Temperature Range	
MAT-04AY, BY	55°C TO +125°C
MAT-04EY	25°C TO +85°C
MAT-04FY,FP,FS	40°C to +85°C
Storage Temperature	
Y Package	–65°C to +150°C
P Package	65°C to +125°C
Lead Temperature (Soldering, 60 sec)	+300°C

PACKAGE TYPE	Θ <sub>jA</sub> (Note 2)	$\Theta_{jC}$	UNITS
14-Pin CERDIP (Y)	108	16	°C/W
14-Pin Plastic DIP (P)	83	39	°C/W
14-Pin SO (S)	120	36	°C/W

### NOTES:

- Absolute maximum ratings apply to both DICE and packaged parts, unless otherwise noted.
- 2.  $\Theta_{jA}$  is specified for worst case mounting conditions, i.e.,  $\Theta_{jA}$  is specified for device in socket for CerDIP and P-DIP packages;  $\Theta_{jA}$  is specified for device solderec to printed circuit board for SO package.

**ELECTRICAL CHARACTERISTICS** at  $T_A = 25^{\circ}C$  unless otherwise noted. Each transistor is individually tested. For matching parameters ( $V_{OS}$ ,  $I_{OS}$ ,  $\Delta h_{FE}$ ) each dual transistor combination is verified to meet stated limits. All tests made at endpoints unless otherwise noted.

			. м.	AT-04/	A/E	M	AT-04E	3/ <b>F</b>	
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Current Gain	h <sub>FE</sub>	$10\mu A \le I_C \le 1mA$ $0V \le V_{CB} \le 30V$ (Note 1)	400	800	_	300	600	_	
Current Gain Match	Δh <sub>FE</sub>	$I_C = 100 \mu A$ $0V \le V_{CB} \le 30V$ (Note 2)		0.5	2	_	1	4	%
Offset Voltage	V <sub>os</sub>	$10\mu A \le I_C \le 1 mA$ $0V \le V_{CB} \le 30V$ (Note 4)	_	50	200	_	100	400	μ۷
Offset Voltage Change vs Collector Current	$\Delta V_{OS}/\Delta I_{C}$	$10\mu A \le I_C \le 1 \text{mA}$ $V_{CB} = 0V$ (Note 4)	_	5	25	_	10	50	μV
Offset Voltage Change vs V <sub>CB</sub>	$\Delta V_{ m OS}/\Delta V_{ m CB}$	$10\mu A \le I_C \le 1mA$ $0V \le V_{CB} \le 30V$ (Note 4)	_	50	100		100	200	μV
Bulk Emitter Resistance	r <sub>BE</sub>	$10\mu$ A $\leq$ $I_C \leq$ 1mA $V_{CB} = 0V$ (Note 5)	_	0.4	0.6		0.4	0.6	Ω
Input Bias Current	, l <sub>B</sub>	$I_C = 100\mu\text{A}$ $0\text{V} \le \text{V}_{CB} \le 30\text{V}$		125	250	_	165	330	nA
Input Offset Current	I <sub>os</sub>	$I_C = 100 \mu A$ $V_{CB} = 0 V$	_	0.6	5		2	13	nA
Breakdown Voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 10μA	40	_	_	40	_		٧
Collector Saturation Voltage	V <sub>CE(SAT)</sub>	$I_B = 100 \mu A$ $I_C = 1 m A$	_	0.03	0.06	_	0.03	0.06	٧
Collector-Base Leakage Current	Гсво	V <sub>CB</sub> = 40V	_	5	_	_	5	-	pA
Noise Voltage Density	e <sub>n</sub>	$V_{CB} = 0V$ $f_O = 10Hz$ $I_C = 1mA$ $f_O = 100Hz$ (Note 3) $f_O = 1kHz$		2 1.8 1.8	3 2.5 2.5		2 1.8 1.8	4 3 3	nV/√Hz
Gain Bandwidth Product	f <sub>T</sub>	$I_C = 1mA$ $V_{CE} = 10V$		300	_	_	300	<del>-</del> .	MHz
Output Capacitance	C <sub>OBO</sub>	V <sub>CB</sub> = 15V I <sub>E</sub> = 0 f = 1MHz		10			10	_	pF
Input Capacitance	C <sub>EBO</sub>	$V_{BE} = 0V$ $I_{C} = 0$ f = 1MHz		40	_	_	40	_	pF

1. Current gain measured at  $I_C = 10\mu A$ ,  $100\mu A$  and 1mA.

2. Current gain match is defined as:  $\Delta h_{FE} = \frac{100 \, (\Delta l_B) \, (h_{FE} \, min)}{l_-}$ 

Sample tested.

Measured at  $I_C = 10 \mu A$  and guaranteed by design over the specified range of I<sub>C</sub>.

5. Guaranteed by design.

**ELECTRICAL CHARACTERISTICS** at  $-25^{\circ}\text{C} \le T_{\text{A}} \le +85^{\circ}\text{C}$  for MAT-04E,  $-40^{\circ}\text{C} \le T_{\text{A}} \le +85^{\circ}\text{C}$  for MAT-04F, unless otherwise noted. Each transistor is individually tested. For matching parameters  $(V_{\text{OS}}, I_{\text{OS}})$  each dual transistor combination is verified to meet stated limits. All tests made at endpoints unless otherwise noted.

			N	IAT-04	JE	N	IAT-04	F	
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
Current Gain	h <sub>FE</sub>	$10\mu$ A ≤ I <sub>C</sub> ≤ 1mA 0V ≤ V <sub>CB</sub> ≤ $30$ V (Note 1)	225	625	_	200	500	_	
Offset Voltage	Vos	10μA ≤ $I_C$ < 1mA 0V ≤ $V_{CB}$ ≤ 30V (Note 3)	_	60	260	_	120	520	μV
Average Offset Voltage Drift	TCV <sub>OS</sub>	$I_C = 100 \mu A$ $V_{CB} = 0 V$ (Note 2)	<del></del>	0.2	1	_	0.4	2	μV/°C
Input Bias Current	l <sub>Β</sub>	$I_C = 100 \mu A$ $0V \le V_{CB} \le 30V$	_	160	445	_	200	500	nA
Input Offset Current	los	$I_C = 100 \mu A$ $V_{CB} = 0 V$		4	20	_	8	40	nA
Average Offset Current Drift	TCI <sub>OS</sub>	$I_{C} = 100 \mu A$ $V_{CB} = 0 V$		50	_		100		pA/°C
Breakdown Voltage	BV <sub>CEO</sub>	I <sub>C</sub> = 10μA	40	_	_	40	_	_	V
Collector-Base Leakage Current	I <sub>CBO</sub>	V <sub>CB</sub> = 40V	_	0.5	_	_	0.5		nA
Collector-Emitter Leakage Current	I <sub>CES</sub>	V <sub>CE</sub> = 40V		5		_	5	_	nA
Collector-Substrate Leakage Current	Ics	V <sub>CS</sub> = 40V	_	0.7	_		0.7	_	nA

**ELECTRICAL CHARACTERISTICS** at  $-55^{\circ}C \le T_{A} \le 125^{\circ}C$  unless otherwise noted. Each transistor is individually tested. For matching parameters ( $V_{OS}$ ,  $I_{OS}$ ) each dual transistor combination is verified to meet stated limits. All tests made at endpoints unless otherwise noted.

			N	AT-04	A	٨	/AT-04	IB		
PARAMETER	SYMBOL	CONDITIONS	MIN	TYP	MAX	MIN	TYP	MAX	UNITS	
Current Gain	h <sub>FE</sub>	$10\mu$ A $\leq$ I <sub>C</sub> $\leq$ 1 mA 0V $\leq$ V <sub>CB</sub> $\leq$ 30V (Note 1)	175	475	_	125	425			
Offset Voltage	Vos	$10\mu A \le I_C \le 1 mA$ $0V \le V_{CB} \le 30V$ (Note 3)	-	70	300		140	600	μV	
Average Offset Voltage Drift	TCV <sub>OS</sub>	$I_C = 100 \mu A$ $V_{CB} = 0 V$ (Note 2)	_	0.2	1	***************************************	0.4	2	μV/°C	
Input Bias Current	l <sub>B</sub>	$I_C = 100\mu A$ $0V \le V_{CB} \le 30V$	_	210	570		235	800	nA	
Input Offset Current	los	$I_C = 100\mu A$ $V_{CB} = 0V$	_	6	30	_	12	60	nA	
Average Offset Current Drift	TCI <sub>OS</sub>	$I_C = 100\mu A$ $V_{CB} = 0V$		50	_	_	100		pA/°C	
Breakdown Voltage	BV <sub>CEO</sub>	$I_C = 10\mu A$	40	_	_	40	_	_	V	
Collector-Base Leakage Current	Ісво	V <sub>CB</sub> = 40V		5	_		5		nA	
Collector-Emitter Leakage Current	I <sub>CES</sub>	V <sub>CE</sub> = 40V	_	100		_	100	_	nA	
Collector-Substrate Leakage Current	lcs	V <sub>CS</sub> = 40V	_	7		_	7	_	nA	

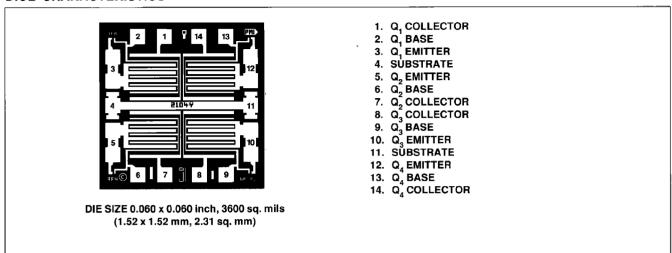
#### NOTES:

3. Measured at  $I_C=10\mu A$  and guaranteed by design over the specified range of  $I_C.$ 

<sup>1.</sup> Current gain measured at  $I_C=10\mu A,\,100\mu A$  and 1 mA.

<sup>2.</sup> Guaranteed by  $V_{OS}$  test (TCV<sub>OS</sub>  $\lesssim V_{OS}/T$  for  $V_{OS} << V_{BE}$ ) T = 298°K for  $T_A = 25$ °C.

#### **DICE CHARACTERISTICS**



**WAFER TEST LIMITS** at  $T_A = +25^{\circ}$ C unless otherwise noted. Each transistor is individually tested. For matching parameters ( $V_{OS}$ ,  $dh_{FE}$ ) each dual transistor combination is verified to meet stated limits. All tests made at endpoints unless otherwise noted.

PARAMETER	SYMBOL	CONDITIONS	MAT-04N LIMITS	UNITS
Current Gain	h <sub>FE</sub>	I <sub>C</sub> = 100μA 0V ≤ V <sub>CB</sub> ≤ 30V	300	MIN
Current Gain Match	∆h <sub>FE</sub>	$I_{\rm C} = 100 \mu A, V_{\rm CB} = 0 V$	4	% MAX
Offset Voltage	V <sub>os</sub>	$10\mu\text{A} \le \text{I}_{\text{C}} \le 1\text{mA}$ $0\text{V} \le \text{V}_{\text{CB}} \le 30\text{V}$ (Note 1)	400	μν ΜΑΧ
Offset Voltage Change vs Collector Current	$\Delta V_{\rm OS}/\Delta I_{\rm C}$	$10\mu$ A $\leq$ I <sub>C</sub> $\leq$ 1mA V <sub>CB</sub> = 0V (Note 1)	50	μν ΜΑΧ
Offset Voltage Change us VCB	$\Delta V_{\rm OS}/\Delta V_{\rm CB}$	$10\mu\text{A} \le \text{I}_{\text{C}} \le 1\text{mA}$ $0\text{V} \le \text{V}_{\text{CB}} \le 30\text{V}$ (Note 1)	200	μν ΜΑΧ
Bulk Emitter Resistance	r <sub>BE</sub>	$10\mu A \le I_C \le 1mA$ $V_{CB} = 0V$ (Note 2)	0.6	Ω ΜΑΧ
Collector Saturation Voltage	V <sub>CE(SAT)</sub>	I <sub>B</sub> = 100μA I <sub>C</sub> = 1mA	0.06	V MAX
Input Bias Current	I <sub>B</sub>	I <sub>C</sub> = 100μA 0V ≤ V <sub>CB</sub> ≤ 30V	330	nA MAX
Input Offset Current	los	I <sub>C</sub> = 100μA V <sub>CB</sub> = 0V	13	nA MAX
Breakdown Voltage	BV <sub>CEC</sub>	I <sub>C</sub> = 10μA	40	V MIN

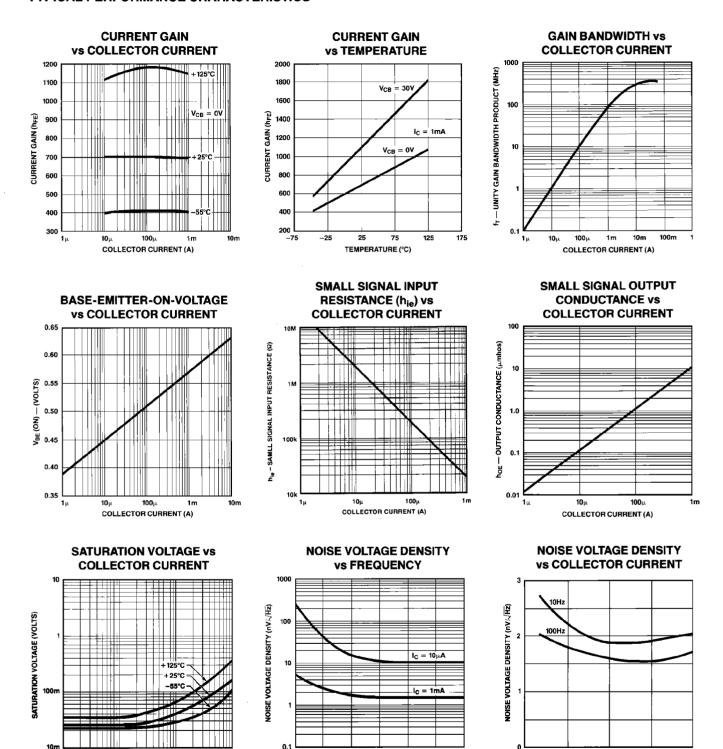
#### NOTE:

Electrical tests are performed at wafer probe to the limits shown. Due to variations in assembly methods and normal yield loss, yield after packaging is not guaranteed for standard product dice. Consult factory to negotiate specifications based on dice lot qualifications through sample lot assembly and testing.

#### **TYPICAL PERFORMANCE CHARACTERISTICS**

10<sub>µ</sub>

COLLECTOR CURRENT (A)



100

FREQUENCY (Hz)

100m

10k

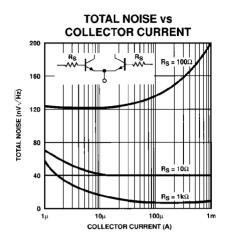
100k

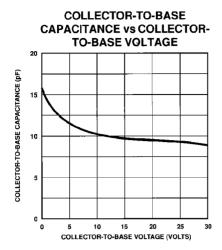
6m

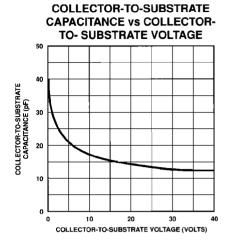
COLLECTOR CURRENT (A)

12m

#### TYPICAL PERFORMANCE CHARACTERISTICS Continued







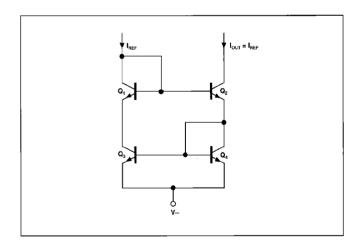
#### **APPLICATION NOTES**

It is recommended that one of the substrate pins (Pins 4 and 11) be tied to the most negative circuit potential to minimize coupling between devices. Pins 4 and 11 are internally connected.

#### **APPLICATIONS**

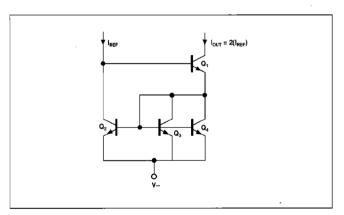
#### **CURRENT SOURCES**

The MAT-04 can be used to implement a variety of high impedance current mirrors as shown in Figures 1, 2, and 3. These current mirrors can be used as biasing elements and load devices for amplifier stages.

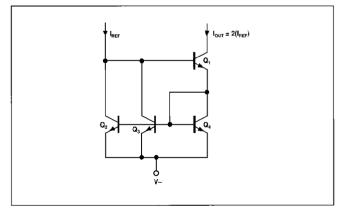


**FIGURE 1:** Unity Gain Current Mirror,  $I_{OUT} = I_{REF}$ 

The unity-gain current mirror of Figure 1, using a MAT-04AY, has an accuracy of better than 1% and an output impedance of over  $100 M\Omega$  at  $100 \mu A$ . Figures 2 and 3 show modified current mirrors designed for a current gain of two, and one-half respectively. The accuracy of these mirrors is reduced from that of the unity-gain source due to base current errors but is still better than 2%.



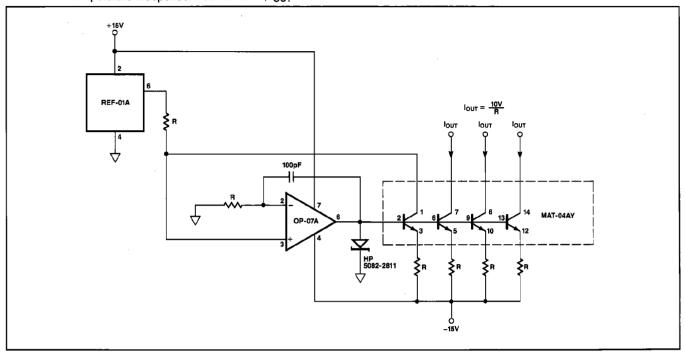
**FIGURE 2:** Current Mirror,  $I_{OUT} = 2(I_{REF})$ 



**FIGURE 2:** Current Mirror,  $I_{OUT} = 2(I_{REF})$ 

Figure 4 is a temperature independent current sink that has an accuracy of better than 1% over the military temperature range at an output current of  $100\mu A$  to 1 mA. The Schottky diode acts as a clamp to insure correct circuit start-up at power on. The resistors used in this circuit should be 1% metal-film type.

FIGURE 4: Temperature Independent Current Sink,  $I_{OUT} = 10V/R\Omega$ 



#### **NONLINEAR FUNCTIONS**

An application where precision matched-transistors are a powerful tool is in the generation of nonlinear functions. These circuits are based on the transistor's logarithmic property which takes the following idealized form:

$$V_{BE} = \frac{kT}{q} \ln \frac{I_C}{I_S}$$

The MAT-04, with its excellent logarithmic conformance, maintains this idealized function over many decades of collector current. This, in addition to the stringent parametric matching of the MAT-04, enables the implementation of extremely accurate log/antilog circuits.

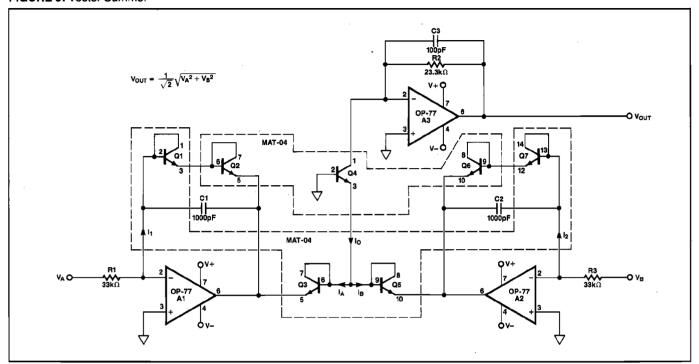
The circuit of Figure 5 is a vector summer that adds and subtracts logged inputs to generate the following transfer function:

$$V_{OUT} = \frac{1}{\sqrt{2}} \sqrt{V_A^2 + V_B^2}$$

This circuit uses two MAT-04AYs and maintains an accuracy of better than 0.5% over an input range of 10mV to 10V. The layout of the MAT-04s reduces errors due to matching and temperature differences between the two precision quad matched-transistors.

Op amps A1 and A2 translate the input voltages into logarithmic valued currents (I<sub>A</sub> and I<sub>B</sub> in Figure 5) that flow through transistor Q<sub>3</sub> and Q<sub>5</sub>. These currents are summed by transistor Q<sub>4</sub> (I<sub>O</sub> = I<sub>A</sub> + I<sub>B</sub> =  $\sqrt{I_1^2 + I_2^2}$ ) which feeds the current-to-voltage converter consisting of op amp A3. To maintain accuracy, 1% metal-film resistors should be used.

FIGURE 5: Vector Summer



#### LOW NOISE, HIGH SPEED INSTRUMENTATION AMPLIFIER

The circuit of Figure 6 is a very low noise, high speed amplifier, ideal for use in precision transducer and professional audio applications. The performance of the amplifier is summarized in Table I. Figure 7 shows the input referred spot noise over the 0-25kHz bandwidth to be flat at 1.2nV/  $\sqrt{\text{Hz}}$ . Figure 8 highlights the low 1/f noise corner at 2Hz.

The circuit uses a high speed op amp, the OP-17, preceded by an input amplifier. This consists of a precision dual matched-transistor, the MAT-02, and a feedback V-to-I converter, the MAT-04. The arrangement of the MAT-04 is known as a "linearized cross quad" which performs the voltage-to-current conversion. The OP-17 acts as an overall nulling amplifier to complete the feedback loop. Resistors R1, R2, and R3, R4 form voltage dividers that attenuate the output voltage swing since the "cross quad" arrangement has a limited input range. Blasing for the input stage is set by zener diode Z1. At low currents the effective zener voltage is about 3.3V due to the soft knee characteristic of the zener diode. This results in a bias current of 530  $\mu$ A per side for the input stage. The gain of this amplifier with the values shown in Figure 6 is:

$$\frac{V_{OUT}}{V_{IN}} = \frac{33000}{R_G}$$

**TABLE I: Instrumentation Amplifier Characteristics** 

Input Noise Voltage Density	G = 1000 G = 100 G = 10	1.2nV/√Hz 3.6nV/√Hz 30nV/√Hz
Bandwidth	G = 500 G = 100 G = 10	400kHz 1MHz 1.2MHz
Slew Rate		40V/μs
Common-Mode Rejection	G = 1000	130dB
Distortion	G = 100 f = 20Hz to 20kHz	0.03%
Settling Time	G = 1000	10µs
Power Consumption		350mW
		·

FIGURE 6: Low Noise, High Speed Instrumentation Amplifier

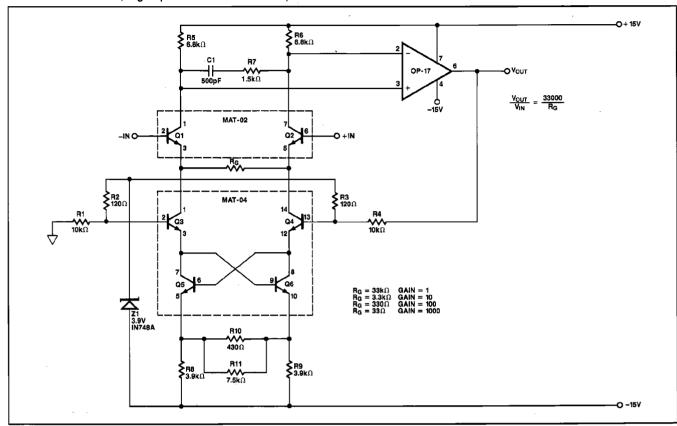
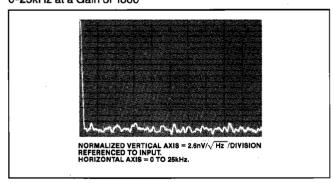


FIGURE 7: Spot Noise of the Instrumentation Amplifier from 0-25kHz at a Gain of 1000



**FIGURE 8:** Low Frequency Noise Spectrum Showing Low 2Hz Noise Corner. Gain = 1000.

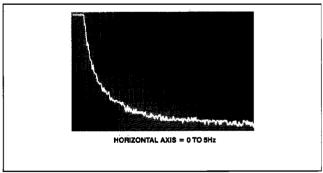
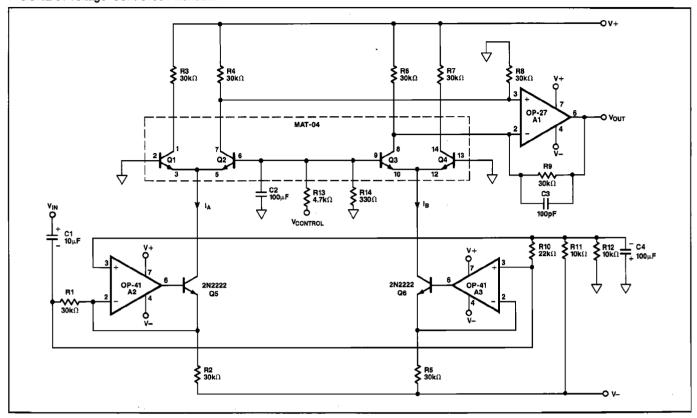


FIGURE 9: Voltage-Controlled Attenuator



#### **VOLTAGE-CONTROLLED ATTENUATOR**

The voltage-controlled attenuator (VCA) of Figure 9, widely used in professional audio circles, can easily be implemented using a MAT-04. The excellent matching characteristics of the MAT-04 enables the VCA to have a distortion level of under 0.03% over a wide range of control voltages. The VCA accepts a 3V RMS input and easily handles the full 20Hz-20kHz audio bandwidth as shown in Figure 10. Noise level for the VCA is more than 110dB below maximum output.

In the voltage-controlled attenuator, the input signal modulates the stage current of each differential pair. Op amps A2 and A3 in conjunction with transistors Q5 and Q6 form voltage-to-current converters that transform a single input voltage into differential currents which form the stage currents of each differential pair. The control voltage shifts the current between each side of the two differential pairs, regulating the signal level reaching the output stage which consists of op amp A1. Figure 11 shows the increase in signal attenuation as the control voltage becomes more negative.

The ideal transfer function for the voltage-controlled attenuator is:

$$V_{OUT}/V_{IN} = \frac{2}{1 + \exp\left(\left(-V_{CONTROL}\right)\left(\frac{R14}{R13 + R14}\right) / \left(\frac{kT}{q}\right)\right)}$$

Where  $k = Boltzmann constant 1.38 \times 10^{-23} \, J/^{\circ} K$ 

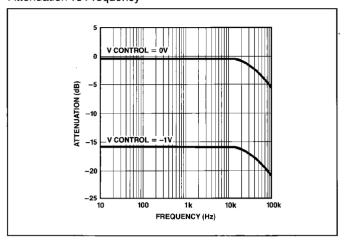
T = temperature in °K

 $q = electronic charge = 1.602 \times 10^{-19}C$ 

From the transfer function it can be seen that the maximum gain of the circuit is 2 (6dB).

To insure best performance, resistors R2 through R7 should be 1% metal film resistors. Since capacitor C2 can see small amounts of reverse bias when the control voltage is positive, it may be prudent to use a nonpolarized tantalum capacitor.

**FIGURE 10:** Voltage-Controlled Attenuator, Attenuation vs Frequency



**FIGURE 11:** Voltage-Controlled Attenuator, Attenuation vs Control Voltage

